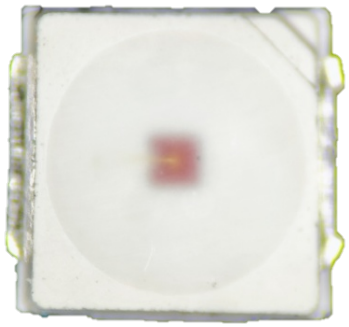
2T12X7RX00036SAA

Ultra high reliability and luminous efficacy ,PLCC LED Series are optimized to be used as lighting for automotive signal lighting designs or signboard.



Applications :

- Automotive Exterior Lighting

Features :

- Package: Ag Plated 2 pad design package with silicone resin
- Dimension: 3.0 mmx3.0 mm
- Chip technology: AlGaInP
- View Angle: 120°
- Color: λdom=616 nm(Red)
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- MSL: Level 2
- Qualifications: The product qualification test based on the guidelines of AEC-Q102

EDISON
Lighting Design Manufacturing Service

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General Information

Ordering Code Format

2	T	12	X7	RX	00	03	6	S	A	A
X1	X2	X3-X4	X5-X6	X7-X8	X9-X10	X11-X12	X13	X14	X15	X16

X1		X2		X3-X4		X5-X6		X7-X8	
Type		Component		Series		Wattage		Color/CCT	
2	Emitter	T	PLCC	12	3030	0.7	0.7W	RX	Red

X9-X10		X11-X12		X13		X14		X15	
CRI(Ra)		Voltage		Leadframe Mode		Leadframe Plating		Model	
00	Single Color	03	3V	6	0.6H 2PIN	S	Silver	A	Automotive

X16
Serial Number
- -

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Absolute Maximum Ratings

Absolute maximum ratings

Parameter		Symbol	Values
Operating Temperature	min. max.	T_{op}	-40 °C 110°C
Storage Temperature	min. max.	T_{stg}	-40 °C 110°C
Junction Temperature	max.	T_j	150°C
Forward current T_J = 25 °C	min. max.	I_F	10 mA 250 mA
Surge Current t ≤ 10 µs; D = 0.005 ; T_J = 25 °C	max.	I_{FS}	300 mA
Reverse voltage T_J = 25 °C	max.	V_R	Not designed for reverse operation
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)		V_{ESD}	2 kV

Notes: Proper current derating must be observed to maintain junction temperature below the maximum at all time.

Characteristics

I_F = 350 mA; T_J = 25 °C

Parameter		Symbol	Values
Peak Wavelength	typ.	λ_{Peak}	621 nm
Dominant Wavelength	min. typ. max.	λ_{dom}	612 nm 616 nm 624 nm
Viewing angle	typ.	φ	120 °
Forward Voltage	min. typ. max.	V_F	2.05 V 2.25 V 2.50 V
Reverse current V_R= 5 V	typ. max.	I_R	0.01 µA 10 µA
Real thermal resistance junction/solder point	typ. max.	$R_{thJS\ real}$	37 K / W 45 K / W
Electrical thermal resistance junction/ solder point with efficiency ηe = 34 %	typ. max.	$R_{thJS\ elec.}$	22 K / W 26 K / W

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Luminous Flux Characteristic

Luminous Flux Characteristics, I_F=200mA , T_J=25˚C

Symbol	Group	Min. Luminous Flux(lm)	Max. Luminous Flux(lm)	Typ. Luminous Intensity(cd)
Φ	30	30	35	10.8
	35	35	40	12.4
	40	40	50	14.0

Note:
The luminous flux performance is guaranteed within published operating conditions. Edison Opto maintains a tolerance of ±10% on flux measurements.

Voltage Bin Structure

Voltage Bin Structure, I_F=200mA , T_J=25˚C

Symbol	Group	Min. Voltage (V)	Max. Voltage (V)
V_F	A90	1.90	2.05
	B05	2.05	2.20
	B20	2.20	2.35

Note:
Forward voltage measurement allowance is ± 0.1V.

Wavelength Bin Structure

Wavelength Bin Structure, I_F=200mA , T_J=25˚C

Symbol	Group	Min. Wd (nm)	Max. Wd (nm)
λ_{dom}	R12	612	616
	R16	616	620
	R20	620	624

Note:
Dominant wavelength meansurement allowance is ± 1nm.

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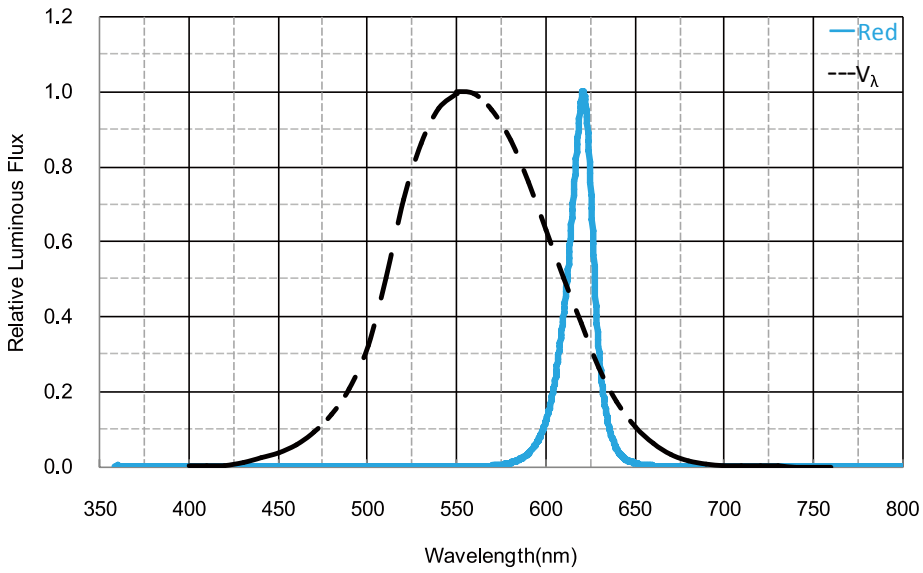
Characteristic Curves

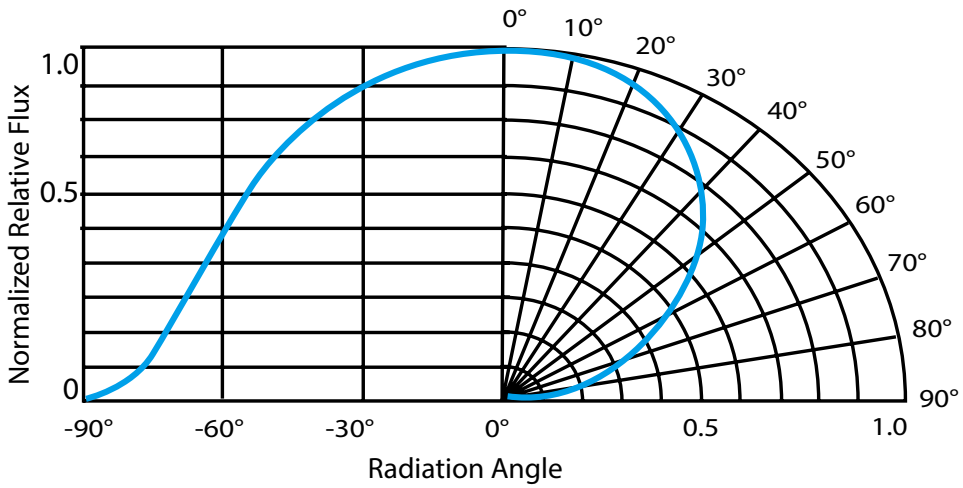
Color Spectrum

I_F =200 mA ; T_J = 25 °C



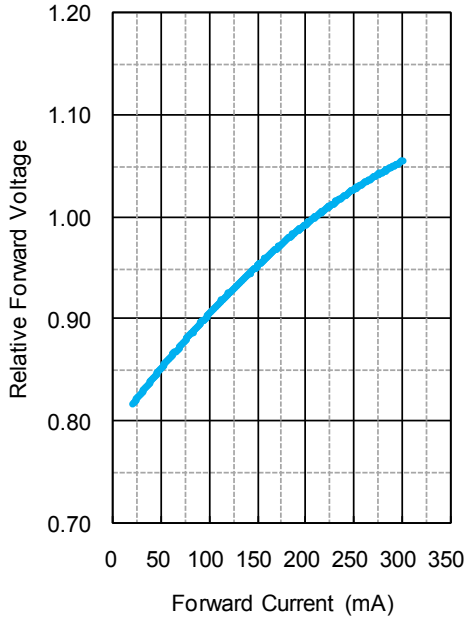
Beam Pattern

I_F =200mA ; T_J = 25 °C



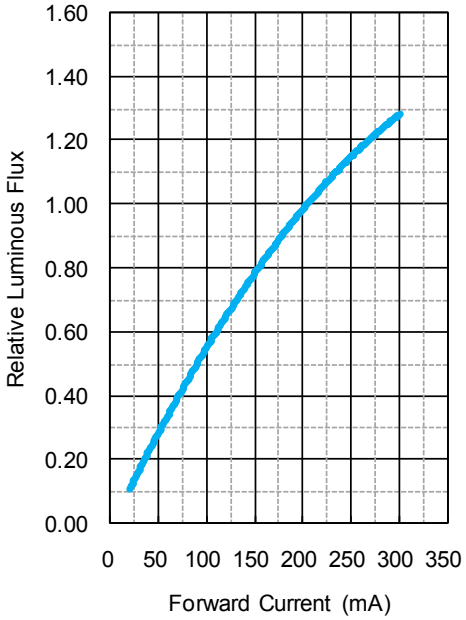
Relative Foward Voltage

$V_F/V_F(200\ mA) = f(V_F); T_J = 25\ °C$



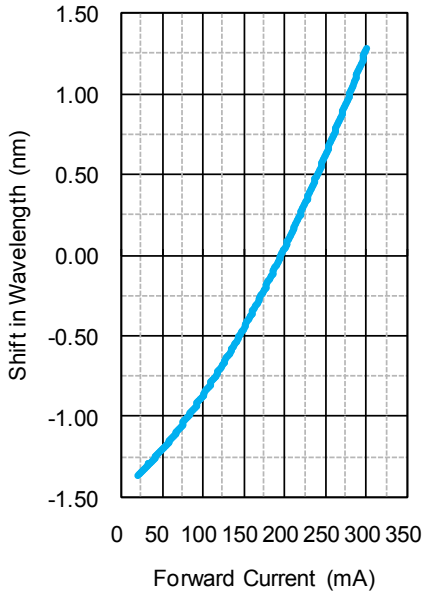
Relative Luminous Intensity

$I_v/I_v(200\ mA) = f(I_v); T_J = 25\ °C$



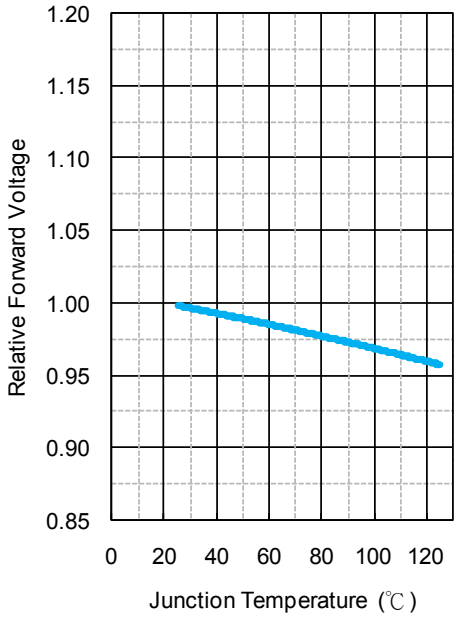
Shift in Dominant Wavelength

$\Delta\lambda_{dom} = \lambda_{dom} - \lambda_{dom}(200\ mA); T_J = 25\ °C$



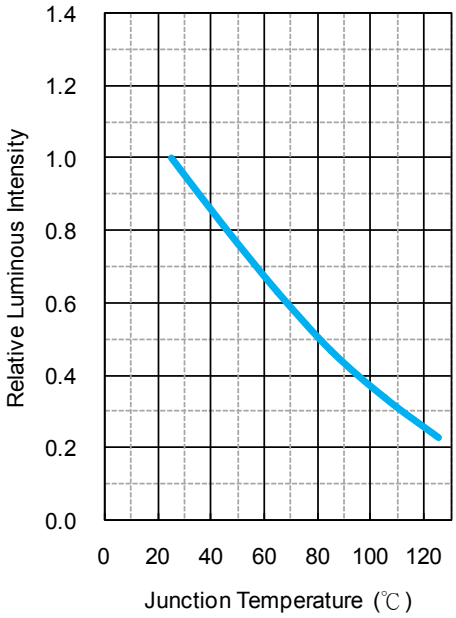
Relative Forward Voltage

$V_F/V_F(25\ °C) = f(V_F);\ I_F = 200\ mA$



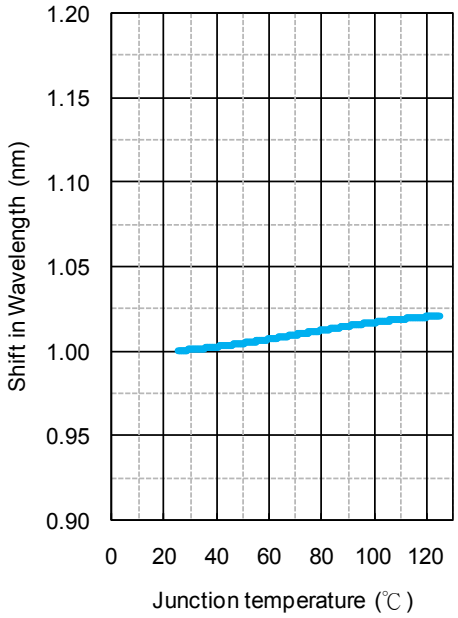
Relative Luminous Intensity

$I_v/I_v(25\ °C) = f(I_v);\ I_F = 200\ mA$



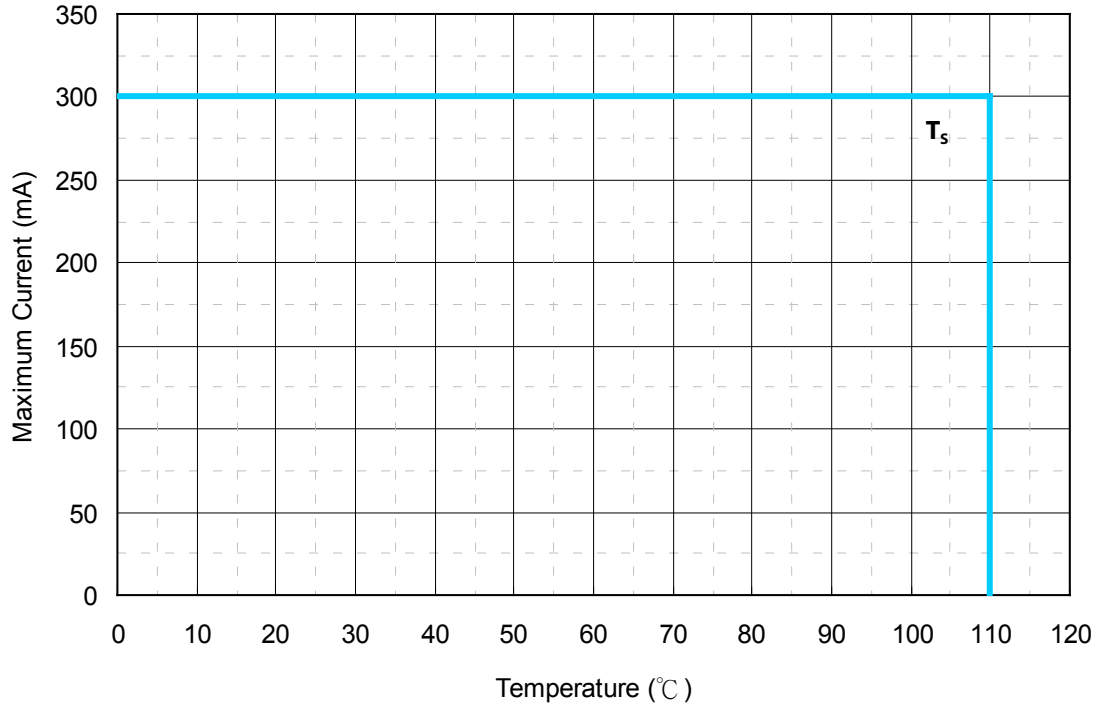
Shift in Dominant Wavelength

$\Delta\lambda_{dom} = \lambda_{dom} - \lambda_{dom}\ (25\ °C);\ I_F = 200\ mA$



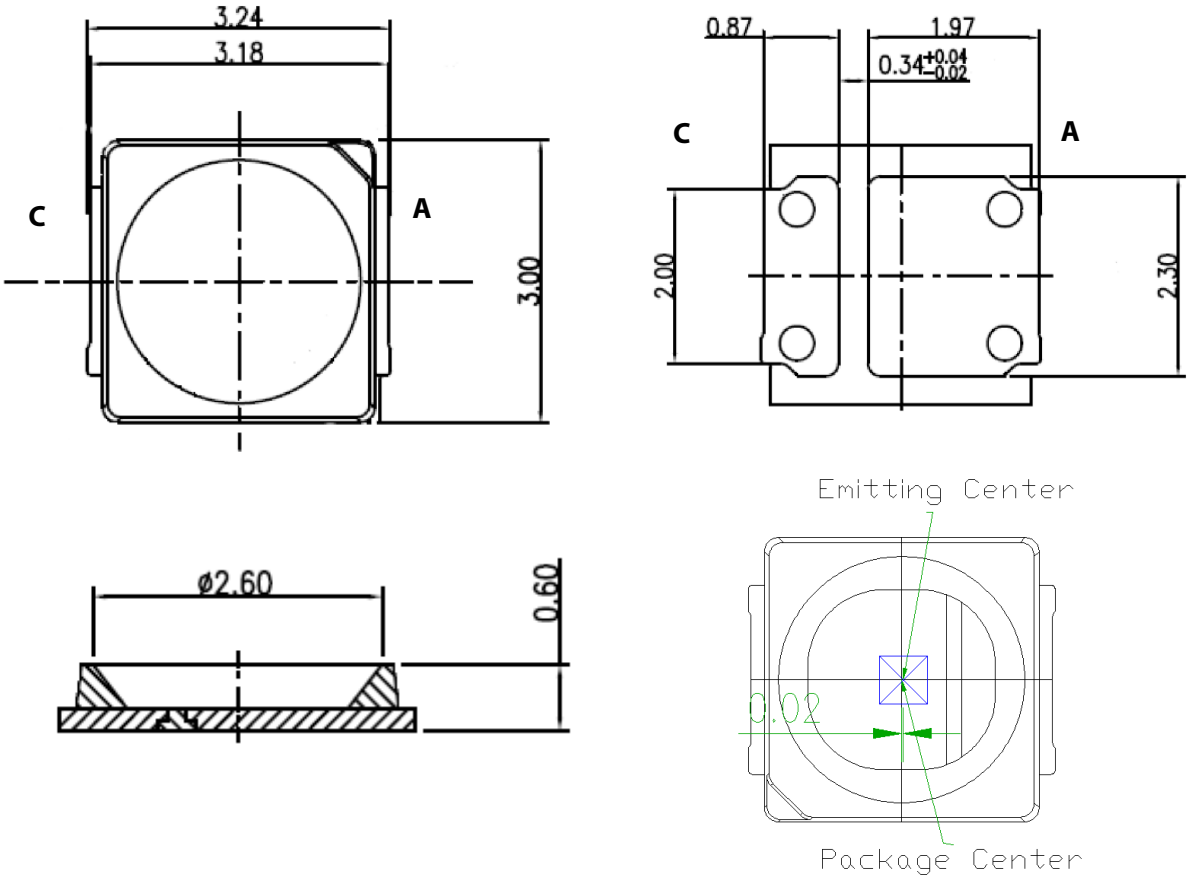
Max. Permissible Forward Current

$I_F = f(T)$

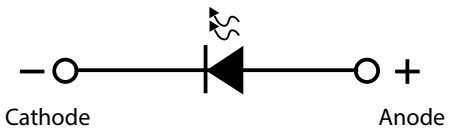


Mechanical Dimensions

Dimensional Drawing

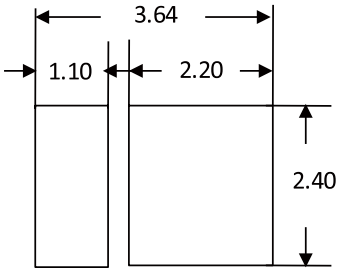


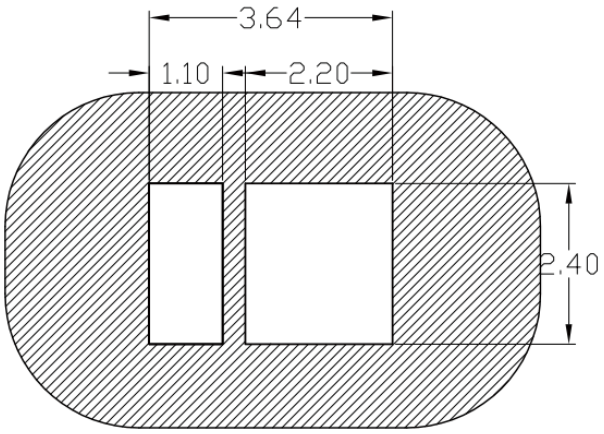
Circuit



Notes:
1. All dimensions are measured in mm.
2. Tolerance : ± 0.1 mm
3. Approximate Weight : 18 mg

Recommended Solder Pad





Paddesign for improved heat dissipation

Solder resist

Notes:
1. All dimensions are measured in mm.
2. Tolerance : ± 0.1 mm

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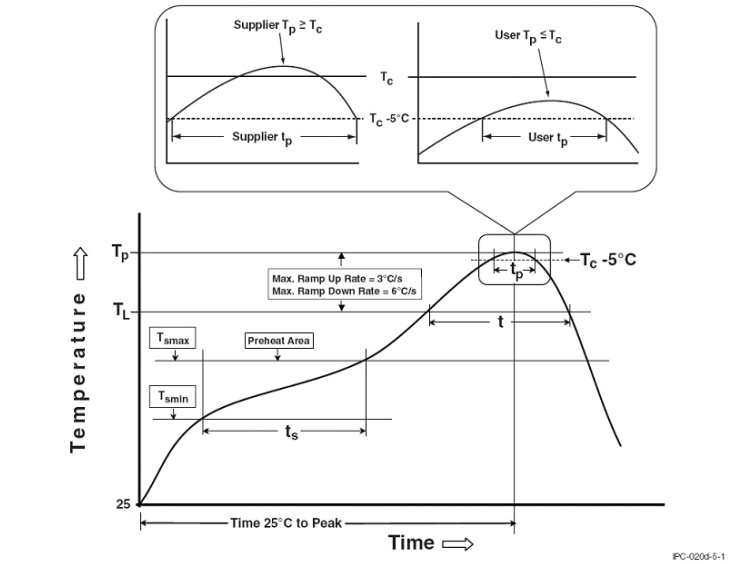
Reflow Profile

The following reflow profile is from IPC/JEDEC J-STD-020D which provided here for reference.



Reflow Profiles

Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Preheat & Soak Temperature min (Tsmin) Temperature max (Tsmax) Time (Tsmin to Tsmax) (ts)	150 °C 200 °C 60-120 seconds
Average ramp-up rate (Tsmax to Tp)	3 °C/second max.
Liquidous temperature (TL) Time at liquidous (tL)	217 °C 60-150 seconds
Peak package body temperature (Tp)	255 °C ~260 °C
Classification temperature (Tc)	260 °C
Time (tp) within 5 °C of the specified classification temperature (Tc)	30 seconds
Average ramp-down rate (Tp to Tsmax)	6°C/second max.
Time 25°C to peak temperature	8 minutes max.

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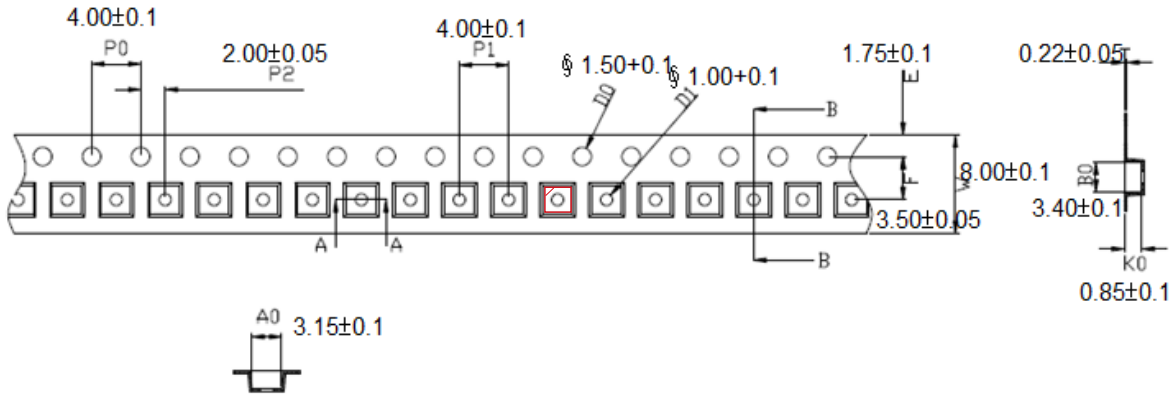
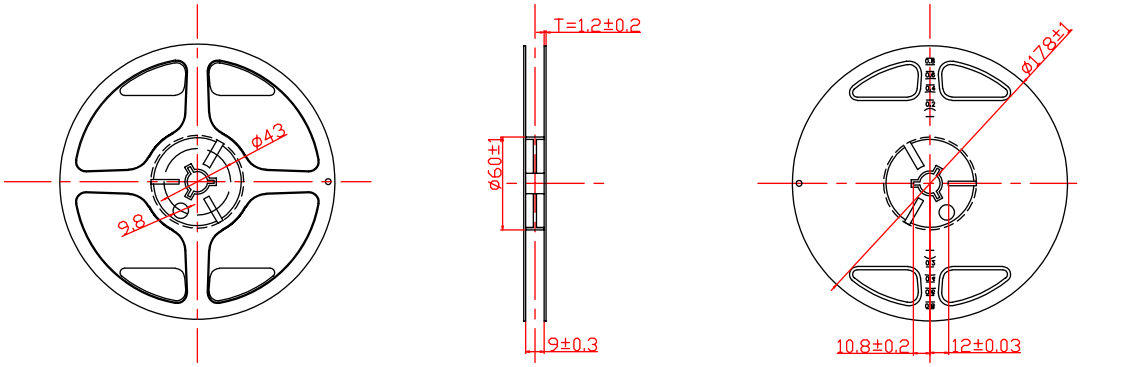
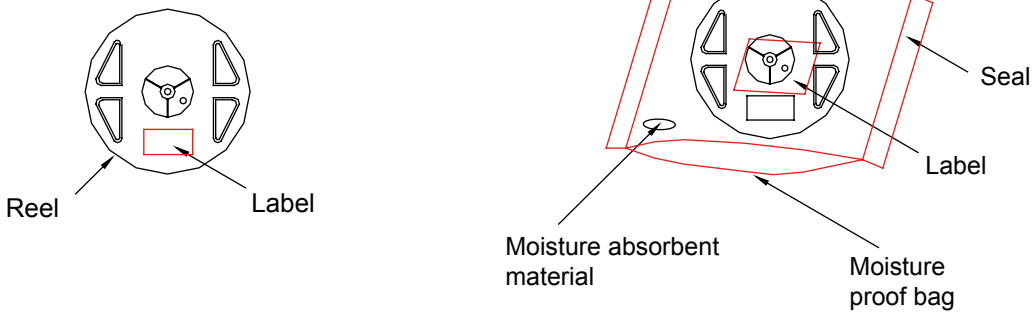
Product Packaging Information



Reel Specification





Item	Quantity	Total	Dimensions(mm)
Reel	4,000pcs	4,000pcs	R=178
Starting with 150pcs empty, and 150pcs empty at the last			

Cautions

(1) Moisture monitoring is vital during the storage of LEDs for if too much moisture is absorbed, interface delamination and optical performance degradation will occur. Therefore, products should be packed in moisture-proof aluminum bags so as to reduce moisture absorption to the lowest degree during transportation and storage. Included moisture-proof aluminum bag are the key indicators that they will change from brown to azure if bags are invaded by moisture.

(2) Soldering process in compliance with the range of the conditions stated above should be conducted after opening the moisture-proof aluminum bag. The rest LEDs should be stored in a hermetically sealed container, silica gel desiccants included. And the original moisture-proof aluminum bags are recommended.

(3) If the "Period After Opening" storage time is too long or silica gel desiccants don't maintain blue any more, baking process should be done once.

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Revision History

Versions	Description	Release Date
1	Establish a Datasheet	2024/01/20

About Edison Opto

Edison Opto is a leading manufacturer of high power LED and a solution provider experienced in LDMS. LDMS is an integrated program derived from the four essential technologies in LED lighting applications- Thermal Management, Electrical Scheme, Mechanical Refinement, Optical Optimization, to provide customer with various LED components and modules. More Information about the company and our products can be found at www.edison-opto.com

www.edison-opto.com

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For technical assistance please contact:
LED.Detective@edison-opto.com.tw